

Tech-X Corporation



May 31, 2011

Tech-X Corporation invites you to visit us at our booth (Booth #541) at the IEEE [Microwave Theory & Techniques Society \(MTT-S\)](#) International Microwave Symposium for 2011 (IMS2011), June 7 - 9, at the Baltimore Convention Center.

We are proud to present the latest release of our electromagnetic plasma simulation software, VORPAL (<http://vorpall.txcorp.com>). VORPAL 4.2.2 includes improved documentation, simplified installation on all platforms, additional collision models, import of user-defined secondary electron yield data, a new photoemission model, delta-F particles for modeling tokamak geometries, and new field updaters.

5621 Arapahoe Ave, Suite A • Boulder, CO 80303
(303) 448-0727 • FAX: (303) 448-7756
www.txcorp.com